

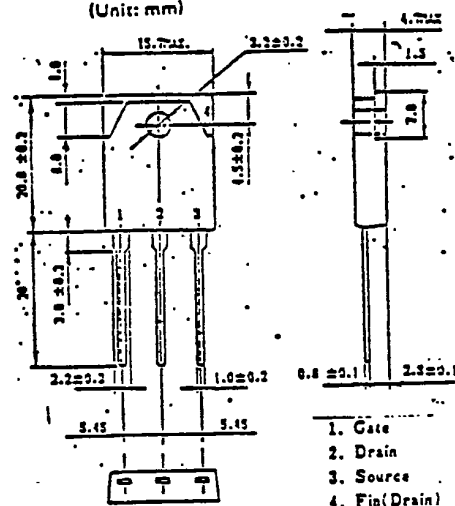
NEC
ELECTRON DEVICE

MOS FIELD EFFECT TRANSISTOR

2SK827

FAST SWITCHING
N-CHANNEL SILICON POWER MOS FET

PACKAGE DIMENSIONS
(Unit: mm)



Features

Suitable for switching power supplies,
actuator controls and pulse circuits
Low $R_{DS(on)}$

Absolute Maximum Ratings ($T_a=25^\circ\text{C}$)

Drain to Source Voltage	V_{DS}	450V
Gate to Source Voltage	V_{GS}	$\pm 20\text{V}$
Continuous Drain Current	$I_D(DC)$	$\pm 18\text{A}$
Pulse Drain Current	$I_D(\text{pulse})$	$*\pm 60\text{A}$
Total Power Dissipation	P_T	3.0W
Total Power Dissipation	P_{T*}	120W
Channel Temperature	T_{ch}	150 °C
Storage Temperature	T_{stg}	-55 to +150 °C
* $P_W \leq 300 \mu\text{s}$, Duty Cycle $\leq 2\%$		
** $T_c=25^\circ\text{C}$		

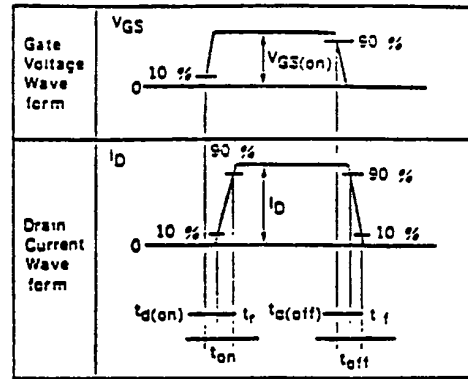
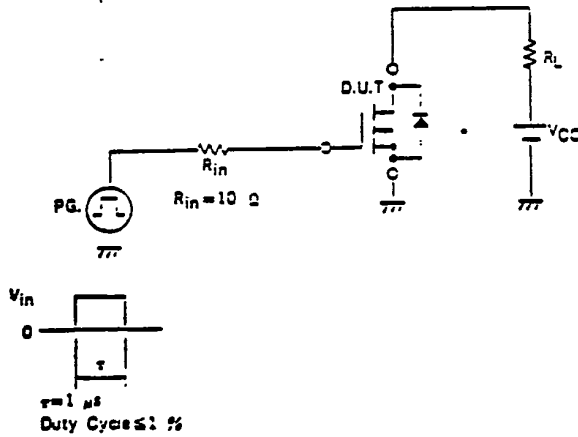
Electrical Characteristics ($T_a=25^\circ\text{C}$)

Characteristics	Symbol	Min.	Typ.	Max.	Unit	Test Conditions
Drain Leakage Current	I_{DSS}			100	μA	$V_{DS}=450\text{V}, V_{GS}=0$
Gate to Source Leakage Current	I_{GSS}			± 100	nA	$V_{GS}=\pm 20\text{V}, V_{DS}=0$
Gate to Source Cutoff Voltage	$V_{GS(off)}$	1.5		3.5	V	$V_{DS}=10\text{V}, I_D=1.0\text{mA}$
Forward Transfer Admittance	y_{fs}	8.0			S	$V_{DS}=10\text{V}, I_D=0.0\text{A}$
Drain to Source On-State Resistance	$R_{DS(on)}$		0.32	0.38	Ω	$V_{GS}=10\text{V}, I_D=0.0\text{A}$
Input Capacitance	C_{iss}		2600		pF	$V_{DS}=10\text{V}, V_{GS}=0$
Output Capacitance	C_{oss}		610		pF	$V_{GS}=0$
Reverse Transfer Capacitance	C_{rss}		140		pF	$f=1.0\text{MHz}$
Turn-On Delay Time	$t_{d(on)}$		20		ns	$I_D=0.0\text{A}$
Rise Time	t_r		40		ns	$V_{GS(on)}=10\text{V}$
Turn-Off Delay Time	$t_{d(off)}$		120		ns	$V_{CC}=150\text{V}$
Fall Time	t_f		55		ns	$R_L=16 \Omega$

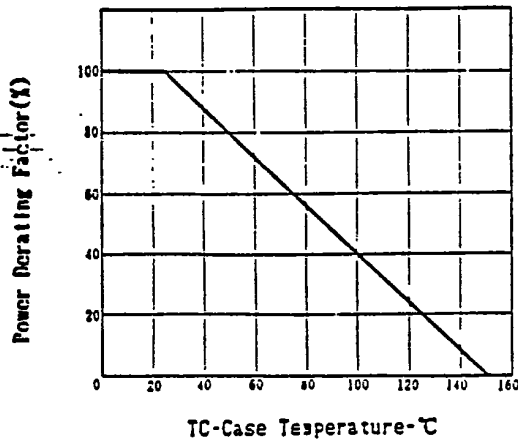
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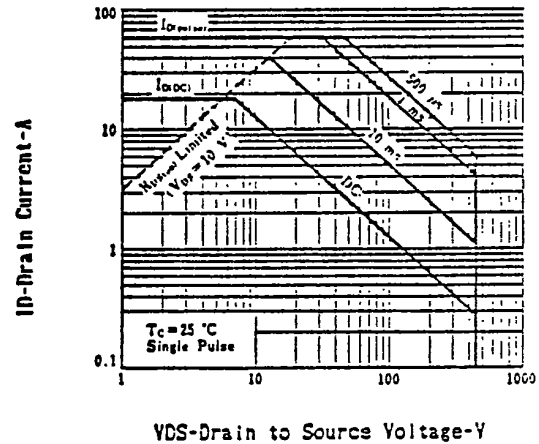
TURN-ON AND TURN-OFF TIME TEST CIRCUIT



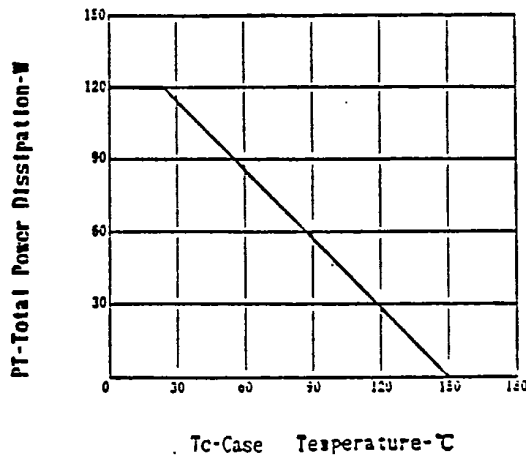
DERATING FACTOR OF FORWARD BIAS SAFE OPERATING AREA



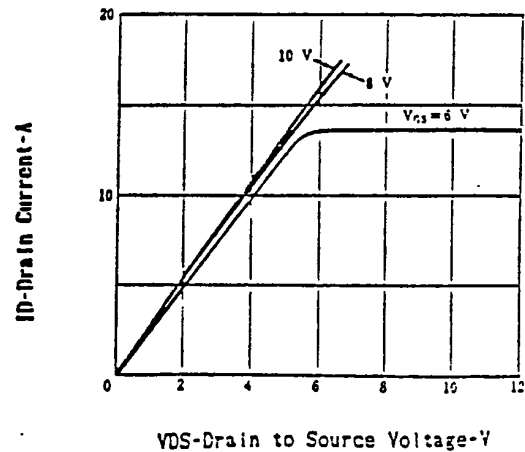
FORWARD BIAS SAFE OPERATING AREA



TOTAL POWER DISSIPATION vs. CASE TEMPERATURE



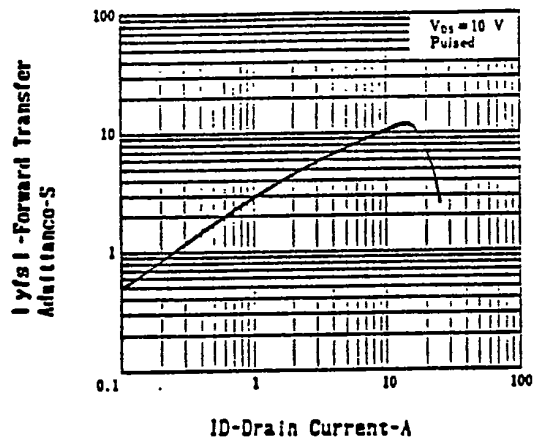
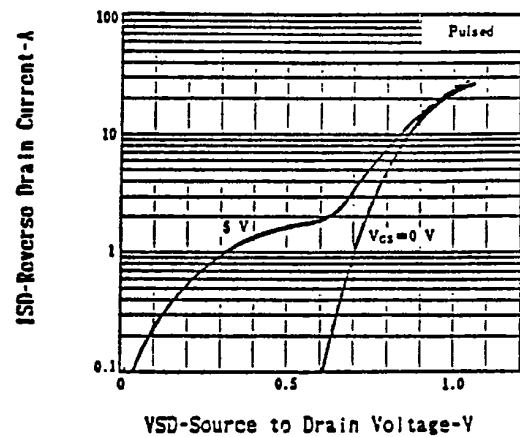
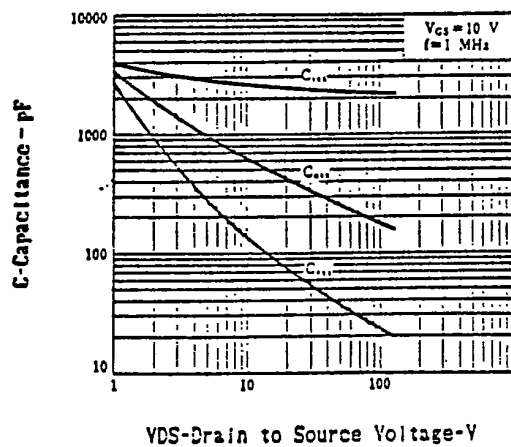
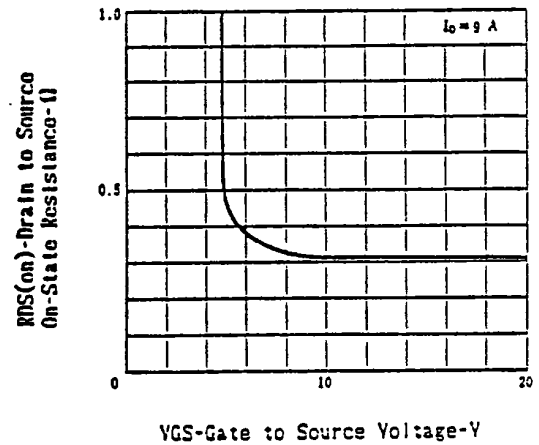
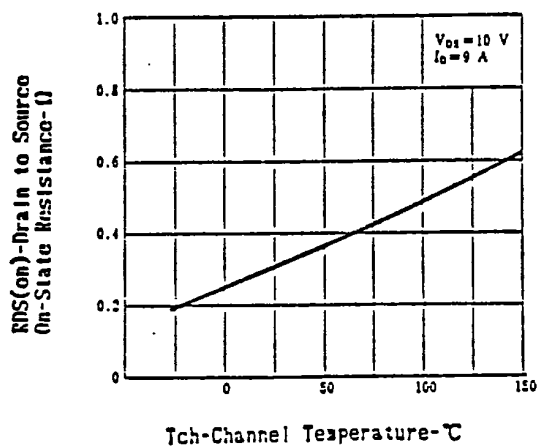
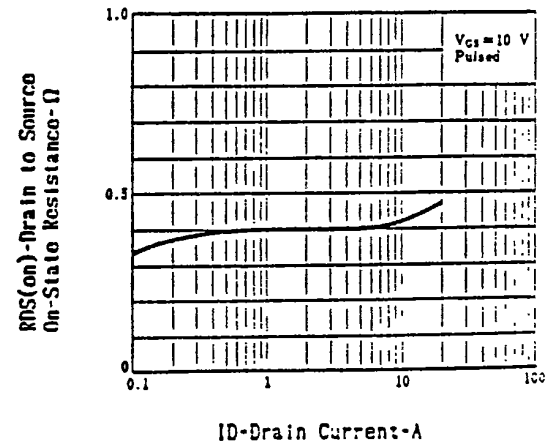
DRAIN CURRENT vs. DRAIN TO SOURCE VOLTAGE



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FORWARD TRANSFER ADMITTANCE
vs. DRAIN CURRENTSOURCE TO DRAIN DIODE
FORWARD VOLTAGECAPACITANCE vs. DRAIN TO
SOURCE VOLTAGEDRAIN TO SOURCE ON-STATE RESISTANCE
vs. GATE TO SOURCE VOLTAGEDRAIN TO SOURCE ON-STATE RESISTANCE
vs. CHANNEL TEMPERATUREDRAIN TO SOURCE ON-STATE RESISTANCE
vs. DRAIN CURRENT

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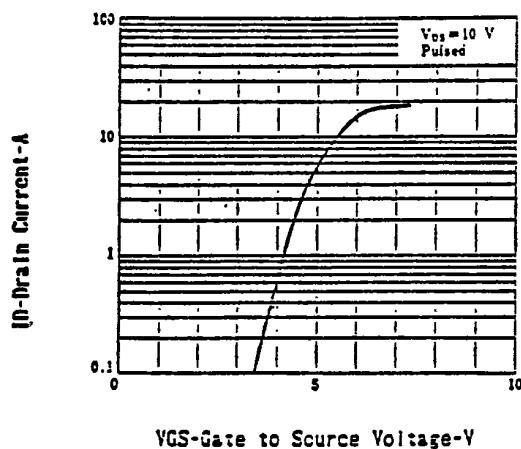
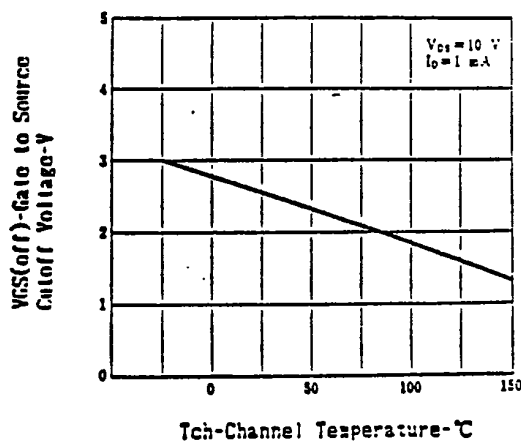
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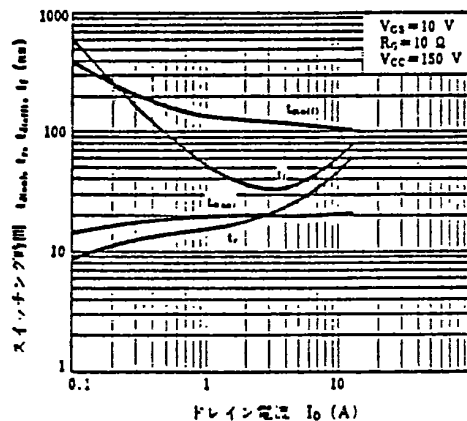
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TRANSFER CHARACTERISTICS

GATE TO SOURCE CUTOFF VOLTAGE
vs. CHANNEL TEMPERATURE

SWITCHING CHARACTERISTICS



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